- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

### description

These devices contain two independent  $J-\overline{K}$  positive-edge-triggered flip-flops. A low level at the preset or clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the J and  $\overline{K}$  inputs meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and  $\overline{K}$  inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding  $\overline{K}$  and tying J high. They also can perform as D-type flip-flops if J and  $\overline{K}$  are tied together.

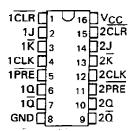
The SN54109 and SN54LS109A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74109 and SN74LS109A are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)

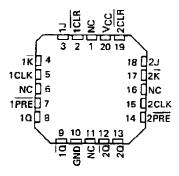
L		iN	PUTS			OUT	PUTS
[	PRE	CLR	CLK	J	K	a	ā
Ţ	L	H	X	х	Х	H	L
l	H	L	×	X	X	L	Н
۱	Ł	L	X	Х	Х	Нţ	Нţ
ı	Н	н	t	L	L	L	Н
ı	н	H	t	Н	L	TOG	GLE
l	н	Н	Ť	Ł	н	വു	$\overline{\alpha}_0$
ĺ	н	н	t	Н	н	Н	L
L	н	н	L	Х	×	<u></u>	₫ <sub>0</sub>

 $<sup>^\</sup>dagger$  The output levels in this configuration are not guaranteed to meet the minimum levels for V<sub>OH</sub> if the lows at preset and clear are near V<sub>1L</sub> maximum. Furthermore, this configuration is nonstable; that is, it will not persist when preset or clear return to their inactive (high) level.

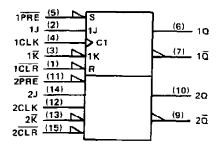
SN54109, SN54LS109A...J OR W PACKAGE SN74109...N PACKAGE SN74LS109A...D OR N PACKAGE (TOP VIEW)



## SN54LS109A . . . FK PACKAGE (TOP VIEW)



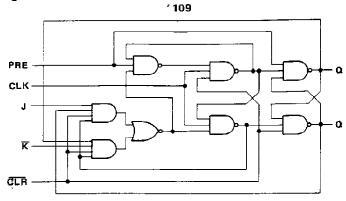
### logic symbol‡



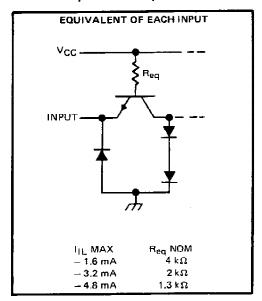
<sup>‡</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

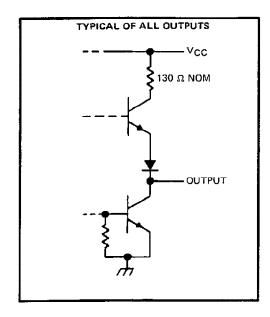
### logic diagram (positive logic)

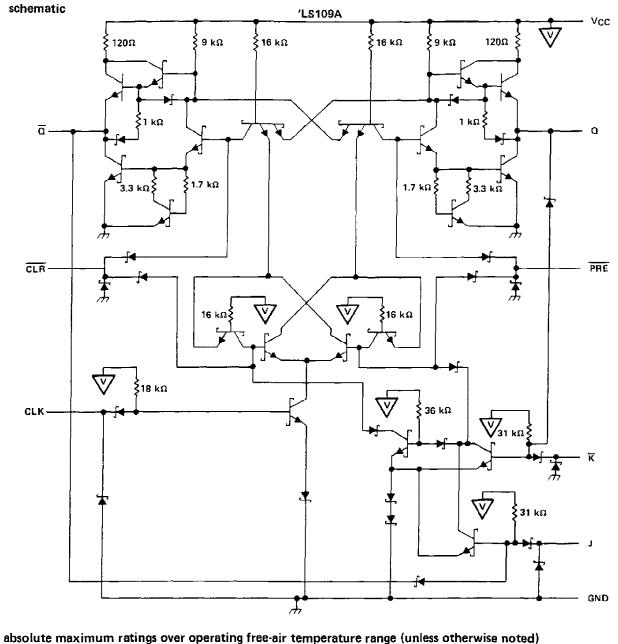


### schematics of inputs and outputs



109





Supply voltage, VCC (see Note 1)		7 V
Input voltage: '109		5.5 V
'LS109A		7 V
Operating free-air temperature range:	SN54',	- 55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range	***************************************	65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



### SN54109, SN74109 DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

### recommended operating conditions

				SN5410	)9		SN7410	9	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				8.0			0.8	V
ІОН	High-level output current				- 0.8			- 0.8	mA
JOL	Low-level output current				16			16	mΑ
	Pulse duration	CLK high or low	20			20			
t <sub>w</sub>	- use duration	PRE or CLR law	20			20			ns
tsu	Input setup time before CLK 1		10			10			ns
th	Input hold time-data after CLK1		6			6			ns
ΤA	Operating free-air temperature		55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAR.	AMETER		TEST CONDITI	onet		SN5410	9		SN7410	9	
1211	AIVIETEIS !		TEBT CONDITI		MIN	TYP‡	MAX	MIN	TYP‡	MAX	דומט
VIK		V <sub>CC</sub> = MIN,	= - 12 mA				- 1.5			- 1.5	V
Vон		V <sub>CC</sub> = MIN, I <sub>OH</sub> = - 0.8 mA	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> ≈ 0.8 V,	2.4	3,4		2.4	3.4		v
VOL		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 16 mA	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = 0.8 V,		0.2	0.4		0.2	0.4	٧
11		V <sub>CC</sub> = MAX,	V <sub>I</sub> = 5.5 V				1		·	1	mA
	J or K						40			40	
1	CLR	V <sub>CC</sub> = MAX,	V. ~ 2.4.V				160			160	_
НІ	PRE or CLK	4GC - MIAA,	v <sub>1</sub> - 2.4 v				80			80	μА
	Jor $\overline{K}$						- 1.6			- 1.6	
1	CLR1	V <sub>CC</sub> = MAX,	V. = 0.4 W				- 4.8			- 4.8	mΑ
'IL	PRE¶	OCC - MAX,	V = 0.4 V				- 3.2			- 3.2	
	CLK		-	<u></u>			- 3.2			-3.2	
los §		V <sub>CC</sub> = MAX			- 30		- 85	- 30	* ***	- 85	mA
ICC#		V <sub>CC</sub> = MAX,	See Note 2		T	9	15		9	15	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open. ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded,

### switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
fmax				25	33		MHz
tPLH .	PRE	O.			10	15	ns
₹₽HL	.,,	ā			23	35	ns
<sup>t</sup> PLH	CLR	ব]	$R_L = 400 \Omega$ , $C_L = 15 \rho F$		10	15	ns
tPHL	OLIT	۵			17	25	ns
₹PLH	CLK	QorQ			10	16	ns
tPHL_	- CER	2510			18	28	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



<sup>&</sup>lt;sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25 \,^{\circ}\text{C}$ .

<sup>&</sup>lt;sup>5</sup> Not more than one output should be shorted at a time.

<sup>1</sup> Clear is tested with preset high and preset is tested with clear high.

<sup>#</sup> Average per flip-flop.

# SN54LS109A, SN74LS109A DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

### recommended operating conditions

		· · · · · · · · · · · · · · · · · · ·	SN54LS109A			SI	N74LS1	09A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
v <sub>CC</sub>	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
Гон	High-level output current		T		- 0.4		••	- 0.4	mA
ТОЦ	Low-level output current				4			8	mA
fclock	Clock frequency		0		25	0		25	MHz
	Pulse duration	CLK high	25		_	25	_		
t <sub>₩</sub>	Pulse duration	PRE or CLR low	25			25			ns
	Beautiful before Cl K t	High-level data	35			35			
t <sub>su</sub>	Setup time before CLK 1	Low-level data	25			25			ns
th .	Hold time-data after CLK †		5			5			ns
TA	Operating free-air temperature		- 55		125	0		70	°c

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	RAMETER		TEST CONDITIO	Not	SI	154LS10	19A	SN	174LS10	9A	
FA	MAINETER	}	IESI COMDITIO	149.	MIN	TYP#	MAX	MIN	TYP‡	MAX	דומט
VIK		VCC - MIN,	I <sub>I</sub> = - 18 mA				<b>– 1.5</b>			_ 1.5	V
Vон		V <sub>CC</sub> = MIN, I <sub>OH</sub> = - 0.4 mA	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = MAX,	2.5	3.4		2.7	3.4		V
		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 4 mA	VIL = MAX,	V <sub>IH</sub> = 2 V,		0.25	0,4		0.25	0.4	V
$V_{OL}$ $V_{CC} = MIN$ , $V_{IL} = MA$		VIL = MAX,	V <sub>1H</sub> = 2 V,					0.35	0.5		
1.	J, K or CLK	Vcc = MAX,	V <sub>1</sub> = 7 V				0.1			0.1	mA
11	CLR or PRE	VCC - MAX,	41-14				0.2			0.2	I IIIA
t	J, R or CLK	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V				20			20	
ΙΗ	CLR or PRE	VCC - WAX,	V  - 2.7 V				40		-	40	μА
	J, K or CLK	VCC = MAX,	V. = 0.4 V				- 0.4			- 0.4	
ŊĻ	CLR or PRE	ACC - MWY	V <sub>I</sub> = 0.4 V				- 0.8			- 0.8	mA
OS§		VCC = MAX,	See Note 4	<u>.</u>	- 20	-	- 100	- 20		- 100	mA
Icc (	Total)	V <sub>CC</sub> = MAX,	See Note 2			4	8		4	8	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions,

NOTE 2: With all outputs open, ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V<sub>O</sub> = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively with the minimum and maximum limits reduced to one half of their stated values.

### switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	мах	UNIT
f <sub>max</sub>				25	33		MHz
<sup>t</sup> PLH	CLR, PRE	Q or Q	$R_L = 2 k\Omega$ , $C_L = 15 pF$		13	25	ns
<sup>t</sup> PHL_	or CLK				25	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>^{\</sup>circ}$  All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. §Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

23-Mar-2012

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
JM38510/30109B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30109SEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	
JM38510/30109SEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	
JM38510/30109SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	
JM38510/30109SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	
M38510/30109B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/30109B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
M38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
M38510/30109SEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	
M38510/30109SEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	
M38510/30109SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	
M38510/30109SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	
SN54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN74109N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74109N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74LS109ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS109AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS109AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS109AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS109ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS109ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS109ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54LS109AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SNJ54LS109AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS109AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS109AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF SN54LS109A, SN54LS109A-SP, SN74LS109A:

Catalog: SN74LS109A, SN54LS109A

Military: SN54LS109A



23-Mar-2012

• Space: SN54LS109A-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

### PACKAGE MATERIALS INFORMATION

14-Jul-2012 www.ti.com

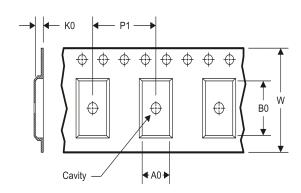
### TAPE AND REEL INFORMATION

### **REEL DIMENSIONS**





### **TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### TAPE AND REEL INFORMATION

### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS109ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS109ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS109ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS109ANSR	SO	NS	16	2000	367.0	367.0	38.0

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